Celebrating #MSP430love

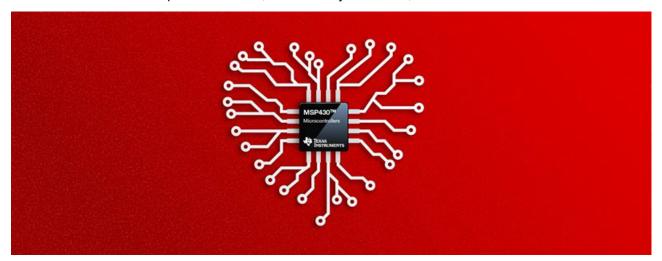


Dave S

One of the things that makes MSP430[™] microcontrollers (MCUs) great is the worldwide community and how much love they show for the platform with their designs, external forum and TI E2E[™] community posts and conversations on social media. TI employees and the community have put together some interesting facts and firsts about the MSP430 MCU – our favorite top 14, in the spirit of the holiday, are listed below.

We'd love to hear about your #MSP430LOVE – share your first MSP430 MCU experiences on this post, on social or in the E2E forum.

- 1. The MSP430 MCU was created in Freising, Germany a town north of Munich.
- 2. TI's MSP430 FRAM MCU portfolio was introduced in 2010 and is now the largest in the industry.
- 3. CapTlvate™ touch technology provides the industry's most noise immune touch sensing solution.
- MSP430 Ultrasonic Sensing Subsystem provides the industry's highest accuracy fully integrated flow measurement solution.
- 5. TI's lowest-power MSP430 MCUs are so low power they can run off grapes.
- 6. MSP430 MCU was the first to introduce low-cost portable development system a \$20 USB stick debugger introduced in 2006.
- 7. The first LaunchPad development kit was designed with an MSP430 MCU and introduced in 2010.
- 8. MSP430 MCUs feature Energytrace™ technology allowing developers to quickly optimize the energy consumption of the MCU.
- 9. TI has shipped over 1 Million LaunchPad kits.
- 10. MSP430 MCUs were used to program the world's smallest satellites with KickSat.
- 11. There are more than 525 different MSP430 microcontrollers on the market today; more than 3,200 if you include all package variants. Find the right one for your application here!
- 12. MSP430 MCUs are featured in almost 300 TI Reference Designs.
- 13. The world's first wearable development kit, the eZ430-Chronos was introduced in 2009.
- 14. MSP430 MCUs have inspired 43Oh.com, a community of over 32,000 of "430" enthusiasts.



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